Amendments to the Claims

Claims 1-21 (Canceled)

Claim 22 (New): A method for manufacturing a semiconductor device, comprising:

preparing a first semiconductor element having first and second surfaces, the first surface being opposite to the second surface, wherein the first surface has a central region on which a second semiconductor element is mountable thereon and a peripheral region on which a plurality of connecting terminals are to be formed thereon;

forming a plurality of first terminals on the central and peripheral regions of the first surface of the first semiconductor element;

covering the first surface of the first semiconductor element by a first sealing resin so that top surfaces of the first terminals are exposed from the first sealing resin;

providing the plurality of connecting terminals on the first terminals formed on the peripheral region of the first surface of the first semiconductor element;

preparing the second semiconductor element as having front and backside surfaces;

forming a plurality of second terminals on the front surface of the second semiconductor element;

covering the front surface of the second semiconductor element by a second sealing resin so that top surfaces of the second terminals are exposed from the second sealing resin; and

mounting the second semiconductor element on the first surface of the first semiconductor element so that the front surface faces the first semiconductor element, wherein the plurality of second terminals of the second semiconductor element are electrically connected with the plurality of first terminals located on the central region of the first semiconductor element.

Claim 23 (New): The method according to claim 22, wherein the plurality of first terminals are connected with the plurality of second terminals by soldered members.

Claim 24 (New): The method according to claim 23, wherein the soldered members include a high temperature solder which has a melting point of 200°C or more.

Claim 25 (New): The method according to claim 22, further comprising:

providing an adhesive member on the backside surface of the second semiconductor element, wherein the adhesive member is heat-conductive.

Claim 26 (New): The method according to claim 22, further comprising:

placing the second semiconductor element on a mounting tape after providing the second sealing resin on the front surface of the second semiconductor element, wherein the mounting tape is stuck on the backside surface of the second

semiconductor element.

Claim 27 (New): A method for manufacturing a semiconductor device, comprising:

preparing a base plate having a heat radiation plate;

mounting a first semiconductor element on the base plate;

forming a plurality of bumps on the base plate;

molding the first semiconductor element with a sealing resin;

mounting a second semiconductor element on a surface of the sealing resin before the sealing resin is solidified; and

solidifying the sealing resin to fix the second semiconductor element on the sealing resin.

Claim 28 (New): The method according to claim 27, wherein the base plate includes an epoxy resin.

Claim 29 (New): The method according to claim 27, wherein the second semiconductor element has front and backside surfaces, the front surface being opposite to the backside surface, the method further comprising:

forming a plurality of terminals on the front surface of the second semiconductor element, wherein the backside surface of the second semiconductor element is in contact with the sealing resin.

Claim 30 (New): A method for mounting first and second semiconductor elements on a base plate, comprising:

preparing the base plate as having a first surface on which the first semiconductor element is mountable thereon and a second surface on which the second semiconductor element is mountable thereon, wherein the first surface is opposite to the second surface, and wherein the second surface has a central region at which the second semiconductor element is mountable thereon and a peripheral region on which a plurality of conductive patterns are formed;

mounting the first semiconductor element on the first surface of the base plate;

preparing the second semiconductor element as having front and backside surfaces;

forming a plurality of terminals on the front surface of the second semiconductor element;

covering the front surface of the second semiconductor element and sidewalls of the terminals by a resin so that top surfaces of the terminals are exposed from the resin;

mounting the second semiconductor element on the central region of the second surface of the base plate after the front surface of the second semiconductor element is covered by the resin, so that the front surface faces the base plate, wherein the plurality of terminals are electrically connected with the plurality of conductive patterns; and

molding the first semiconductor element with a sealing resin.

Claim 31 (New): The method according to claim 30, wherein the second semiconductor element is not molded by the sealing resin.

Claim 32 (New): The method according to claim 30, further comprising:

placing the second semiconductor element on a mounting tape after providing the sealing resin on the front surface of the second semiconductor element, wherein the mounting tape is stuck on the backside surface of the second semiconductor element.

Claim 33 (New): The method according to claim 30, wherein the base plate includes epoxy resin.

Claim 34 (New): A semiconductor device comprising:

a BGA (ball grid array) type semiconductor device including a base plate and a plurality of bumps formed on a backside surface of the base plate; and

a CSP (chip size packaged) type semiconductor device mounted on an area of the backside surface of the base plate of said BGA type semiconductor device which does not have any bumps formed thereon,

said CSP type semiconductor device having a plurality of terminals which are formed on a front surface thereof and which are electrically connected to the plurality of bumps.

Claim 35 (New): The semiconductor device of claim 34, wherein the plurality of terminals of said CSP type semiconductor device are electrically connected to the plurality of bumps via wiring patterns formed on the backside surface of the base plate.

Claim 36 (New): The semiconductor device of claim 35, wherein the plurality of terminals of said CSP type semiconductor device are coupled to the wiring patterns via solder joints.

Claim 37 (New): The semiconductor device of claim 34, wherein said CSP type semiconductor device is mounted on said BGA type semiconductor device so that the front surface of said CSP type semiconductor device faces the backside surface of the base plate.

Claim 38 (New): The semiconductor device of claim 34, wherein the backside surface of said BGA type semiconductor device is mounted to a printed circuit board via the plurality of bumps, and said CSP type semiconductor device as mounted on the backside surface of the base plate has a thickness less than a thickness of the plurality of bumps.

Claim 39 (New): A semiconductor device comprising:

a BGA (ball grid array) type semiconductor device including

a first semiconductor element mounted on a first surface of a base plate, the base plate having a second surface opposite to the first surface, and

solder bumps on the second surface of the base plate, the solder bumps being electrically connected through the base plate to the first semiconductor element, the second surface having an area without solder bumps; and

a CSP (chip size packaged) type semiconductor device mounted on the second surface of the base plate, said CSP type semiconductor device including

a second semiconductor element having a main surface,

a plurality of terminals on the main surface, and

a resin covering the main surface of the second semiconductor element and side surfaces of the plurality of terminals.

Claim 40 (New): The semiconductor device of claim 39, wherein the plurality of terminals of said CSP type semiconductor device are electrically connected to the solder bumps via wiring patterns formed on the second surface of the base plate.

Claim 41 (New): The semiconductor device of claim 40, wherein the plurality of terminals of said CSP type semiconductor device are coupled to the wiring patterns via solder joints.

Claim 42 (New): The semiconductor device of claim 39, wherein said CSP type

semiconductor device is mounted on the second surface of said base plate so that the main surface of the second semiconductor element faces the second surface of the base plate.

Claim 43 (New): The semiconductor device of claim 39, wherein the second surface of the base plate is mounted to a printed circuit board via the solder bumps, and the second semiconductor element as mounted on the second surface of the base plate has a thickness less than a thickness of the solder bumps.

Claim 44 (New): The semiconductor device of claim 39, wherein a thickness of said CSP type semiconductor device is less than a thickness of the solder bumps.